

On page 6, lines 10, 11, 14, and 15 replace “die” with “microelectronic die”.

On page 7, lines 2 and 5 replace “die” with “microelectronic die”.

On page 6, lines 12, 15, 16, and 20 replace “substrate” with “package substrate”.

On page 7, line 11 replace “is flexible” with “may vary”.

IN THE CLAIMS

2. The process of Claim 1 further comprising fabricating the heat sink from a metal alloy having precipitating constituents.

3. The process of Claim 1 further comprising affixing the heat sink to a microelectronic package including a die affixed to a carrier substrate.

11. The process of Claim 8 further comprising fabricating the heat sink from an aluminum alloy.

12. The process of Claim 8 further comprising fabricating the heat sink from a copper alloy.

15. The process of Claim 14 further comprising fabricating the heat sink from a metal alloy with secondary re-crystallization grain growth.

17. The process of Claim 14 further comprising affixing the heat sink to a microelectronic package which includes a die coupled to a package substrate, the

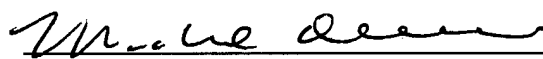
thermal conductivity of the heat sink improved by reducing the grain boundaries that obstruct the movement of atomic and molecular species.

If there are any additional charges, please charge Deposit Account No. 02-2666.

Respectfully submitted,

BLAKELY, SOKOLOFF, TAYLOR & ZAFMAN LLP

Dated: 4/12, 2001



Michael A. Bernadicou
Reg. No. 35,934

12400 Wilshire Blvd.
Seventh Floor
Los Angeles, CA 90025-1026
(408) 720-8300